

L Number	Hits	Search Text	DB	Time stamp
1	177	(438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 14:57
2	27	rcc and bump	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:35
4	52	rcc and solder	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:35
-	83	((flip-chip and resin) and photosensitive) and laminated	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 11:42
-	4	((flip-chip and resin) and photosensitive) and rcc	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:00
-	5	6255039.URPN.	USPAT	2003/03/16 09:36
-	11	("3319317" "3778900" "4642160" "4672020" "4915983" "4952528" "5334487" "5354593" "5451721" "5595858" "5744285").PN.	USPAT	2003/03/16 09:39
-	202	(flip-chip and resin) and photosensitive	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:14
-	690	438/108.ccls.	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 10:56
-	338	438/108.ccls. and resin	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:25
-	328	(438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 10:56
-	163	((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:25
-	0	20020070459.URPN.	USPAT	2003/03/16 10:36

-	722	438/613.ccls.	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:11
-	319	438/613.ccls. and resin	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:11
-	138	(438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 14:57
-	95	((438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:12
-	1455	438/637.ccls.	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:11
-	86	438/637.ccls. and resin	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:11
-	82	(438/637.ccls. and resin) not (((438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:16
-	33	((438/637.ccls. and resin) not (((438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:15
-	30	rcc and solder	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:17

-	25	(rcc and solder) not ((438/637.ccls. and resin) not (((438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not (((438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:17
-	19	rcc and bump	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:32

-	208	((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:26
-	117	((flip-chip and resin) and photosensitive) and laminated	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 11:43

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2	27	rcc and bump	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:35
4	52	rcc and solder	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:35
5	41	((438/637.ccls. and resin) not (((438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not (((438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 17:16